

# Weekly Report for YiYu Shi's work in week3

January 29, 2006

## **1 Work1: Finish the implement and speedup of the code for thermal via optimization**

The first work of this week is to implement and speed up the code for thermal via optimization. Also, several numerical experiments have been done and the results are to some extent satisfactory. We are now gathering data and the related figures.

## **2 Work2: Read the thermal-aware routing paper**

I have read Sachin's paper on thermal-aware routing and have discussed with Hao. I am trying to figure out if the circuit simulation method can be applied to this kind of problem.